Electronic Supplementary Material (ESI) for Nanoscale.

Supporting Information

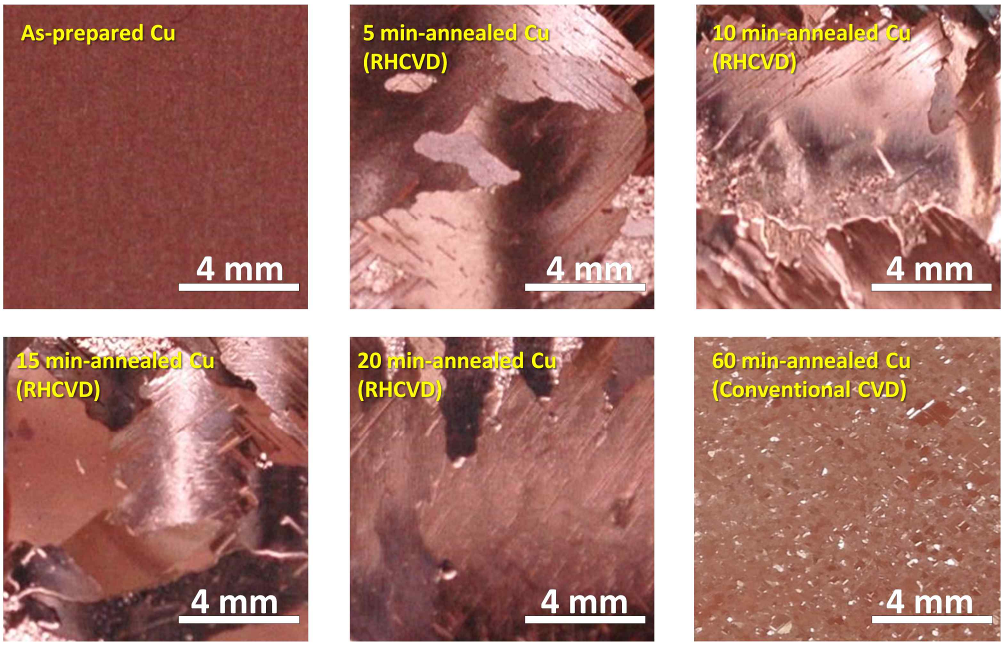

Fig. S1 **Comparison of grain size of the Cu.** The photographs show grain size evolution behaviors of polycrystalline Cu foils with annealing at 1000 °C for 5~20 min by RHCVD and for 60 min by CVD, respectively. The images of the copper foils were taken after annealing process, the surface of which was etched in APS solution of 1 hr.